## IC149 Series (SMT)

## QFP/TQFP - 144 Pins (36x36) 0.5mm pitch

#### **Specifications**

Insulation Resistance: 500MW at 150V DC

Withstanding Voltage:  $100V_{\rm eff}$  to  $700V_{\rm eff}$  for 1 minute Contact Resistance: 30mW max. at 10mA and 20mV

Operating Temp. Range: -25°C to +85°C Reflow-soldering Temp.: 220°C for 60 seconds 20 insertions maximum Mating Cycles:

Solvent Durability:

Allowable Torque (max.): - for 1-time screw connection = max 0.147 Nm

- for repetitive screw connection = min 0.078 Nm

max 0.098 Nm

#### Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0

Contact: Beryllium Copper (BeCu)

SnPb  $2.0 \sim 4.0 \mu m$  over  $2.5 \sim 4.5 \mu m$  Ni = S5

Au  $0.3\mu m$  min. over  $2.5 \sim 4.5\mu m$  Ni = B5

#### Part Number (Details)

IC149 144 - \*45 - \*5

Series No.

No. of Contact Pins

**Positioning Pins:** 

0 = Without Pins

1 = With Pins

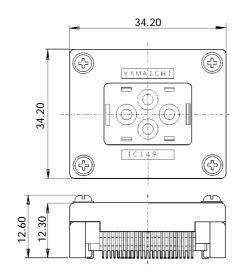
**Contact Plating:** 

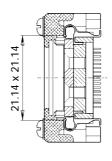
S = SnPb (for IC-socket Use)

B = Gold (for Adapter Use)

### Compatible Emulation-Adapter ICP-144-1

#### Outline Socket Dimensions (Reference Only)





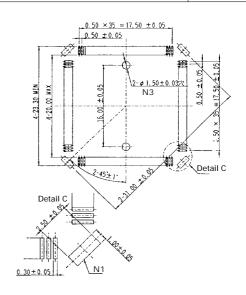
- 1. Ensure a clean contact area. Fluxes, dust and other impurifications may cause corrosion and contact problems
- 2. This Socket is not for automatic production. It is particulary suitable for the development of software stored in ROM and for testing LSI-IC's.
- 3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
- 4. If using the Socket with an Adapter, please use the gold-plated

#### IC - Dimensions

# □20,00 ± 0.2 20mm x 20mm 22.00 0,40 0, 20± 0, 05 21-00 ± 0, 2

Socket PCB-Layout

Top View from Socket



#### Notes

- N1: Metal soldering Tab Clip. Socket may be stabilized
- by soldering (Reflow) in these 4 areas
- N3: These holes are only necessary for use with positioning pins.

## IC149 Series (SMT)

## QFP/TQFP - 144 Pins (36x36) 0.5mm pitch

#### **Specifications**

Insulation Resistance:  $500M\Omega$  at 150V DC

Withstanding Voltage:  $100V_{eff}$  to  $700V_{eff}$  for 1 minute Contact Resistance:  $30m\Omega$  max. at 10mA and 20mV

Operating Temp. Range: -25°C to +85°C
Reflow-soldering Temp.: 220°C for 60 seconds
Mating Cycles: 20 insertions maximum

Solvent Durability: Freon

Allowable Torque (max.): - for 1-time screw connection = max 0.147 Nm

- for repetitive screw connection = min 0.078 Nm

max 0.098 Nm

#### Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0

Contact: Beryllium Copper (BeCu)

Plating: SnPb  $2.0 \sim 4.0 \mu m$  over  $2.5 \sim 4.5 \mu m$  Ni = S5

Au  $0.3\mu m$  min. over  $2.5 \sim 4.5\mu m$  Ni = B5

Part Number (for IC-use)

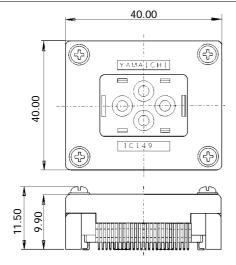
IC149-144KS-11453-0 (w/o pos. pins) IC149-144KS-11453-1 (with pos. pins)

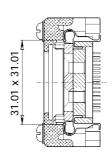
Part Number (for Adapter-use)

IC149-144KS-11453-0B (w/o pos. pins) IC149-144KS-11453-1B (with pos. pins)

Compatible Emulation-Adapter ICP-160-1

#### Outline Socket Dimensions (Reference Only)





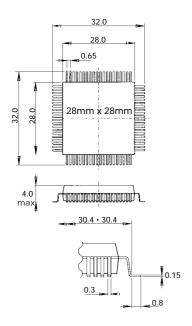
#### Remarks

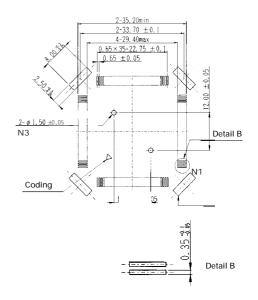
- 1. Ensure a clean contact area. Fluxes, dust and other impurifications may cause corrosion and contact problems.
- 2. This Socket is not for automatic production. It is particulary suitable for the development of software stored in ROM and for testing LSI-IC's.
- 3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
- 4. If using the Socket with an Adapter, please use the gold-plated Socket version

#### IC - Dimensions

Socket PCB-Layout

Top View from Socket





#### Notes

- N1: Metal soldering Tab Clip. Socket may be stabilized
- by soldering (Reflow) in these 4 areas.
- N3: These holes are only necessary for use with positioning pins.